Sumikon® PM-TX230

Phenolic

SBHPP

Message:

SUMIKON PM-TX230 is a Heat dissipative themoset molding compounds, Non-electrical insulative based on Phenolic polymer. It is supplied in the form of Granular/Molding Powder for Molding.

General Information			
Filler / Reinforcement	Inorganic filler		
Appearance	Black		
Forms	Powder Particles		
Processing Method	Resin transfer molding		
Physical	**Nominal Value**	**Unit**	**Test Method**
Specific Gravity	1.83	g/cm³	JIS K6911
Molding Shrinkage - Flow	0.16	%	JIS K6911
Mechanical	**Nominal Value**	**Unit**	**Test Method**
Flexural Modulus	19000	MPa	JIS K6911
Flexural Strength	95.0	MPa	JIS K6911
Impact	**Nominal Value**	**Unit**	**Test Method**
Charpy Notched Impact Strength	2.8	kJ/m²	JIS K6911
Thermal	**Nominal Value**	**Unit**	
Thermal Conductivity	3.0	W/m/K	